

Features

- Fast Switching
- Low Gate Charge and $R_{DS(on)}$
- Low Reverse transfer capacitances


Product Summary

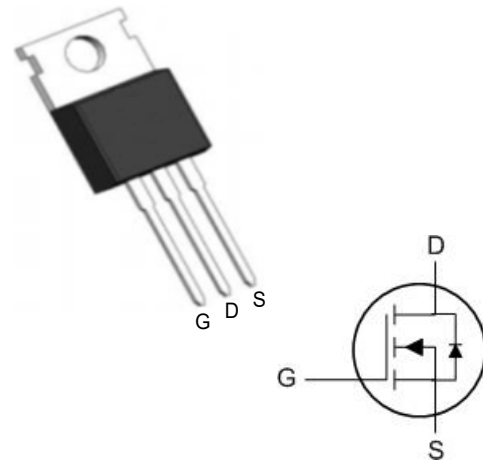
BVDSS	RDSON	ID
120V	10mΩ	70A

Applications

- DC-DC converter
- Portable Equipment
- Power management

100% DVDS Tested

100% Avalanche Tested

TO220 Pin Configuration

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	120	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	70	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	35	A
I_{DM}	Pulsed Drain Current ²	220	A
EAS	Single Pulse Avalanche Energy ³	210	mJ
I_{AS}	Avalanche Current	---	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	85	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	---	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1.47	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	120	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	---	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=84A$	---	10	12.5	m Ω
		$V_{GS}=4.5V, I_D=84A$	---	11.5	15	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.4	1.8	2.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=120V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=120V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=84A$	---	---	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	---	---	Ω
Q_g	Total Gate Charge		---	31	---	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=60V, V_{GS}=10V, I_D=20A$	---	9.4	---	
Q_{gd}	Gate-Drain Charge		---	7.5	---	
$T_{d(on)}$	Turn-On Delay Time		---	15	---	ns
T_r	Rise Time	$V_{DD}=60V, R_{G_ext}=5\Omega,$	---	10	---	
$T_{d(off)}$	Turn-Off Delay Time	$V_{GS}=10V, I_D=20A$	---	32	---	
T_f	Fall Time		---	9	---	
C_{iss}	Input Capacitance		---	1807	---	pF
C_{oss}	Output Capacitance	$V_{DS}=60V, V_{GS}=0V, f=1\text{MHz}$	---	212	---	
C_{rss}	Reverse Transfer Capacitance		---	6	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	60	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=84A, T_J=25^\circ\text{C}$	---	---	1.4	V
t_{rr}	Reverse Recovery Time	$I_F=40A, di/dt=100A/\mu\text{s},$	---	60	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	100	---	nC

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

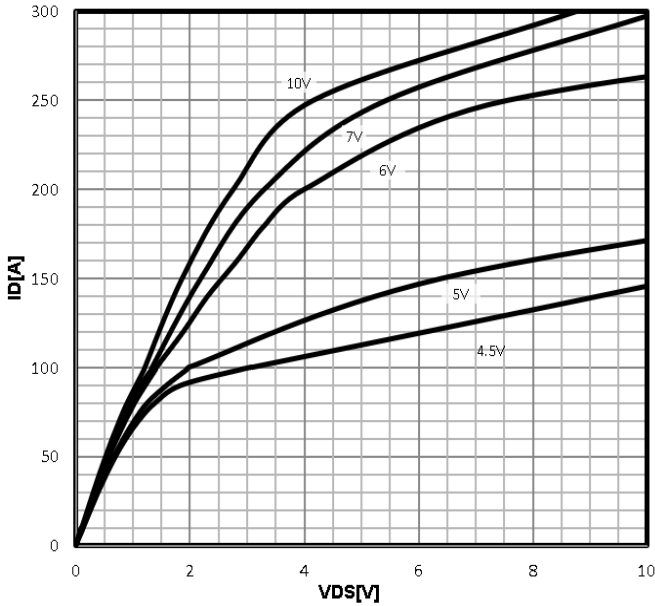
3. The EAS data shows Max. rating. The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.5\text{mH}$,

4. The power dissipation is limited by 150°C junction temperature

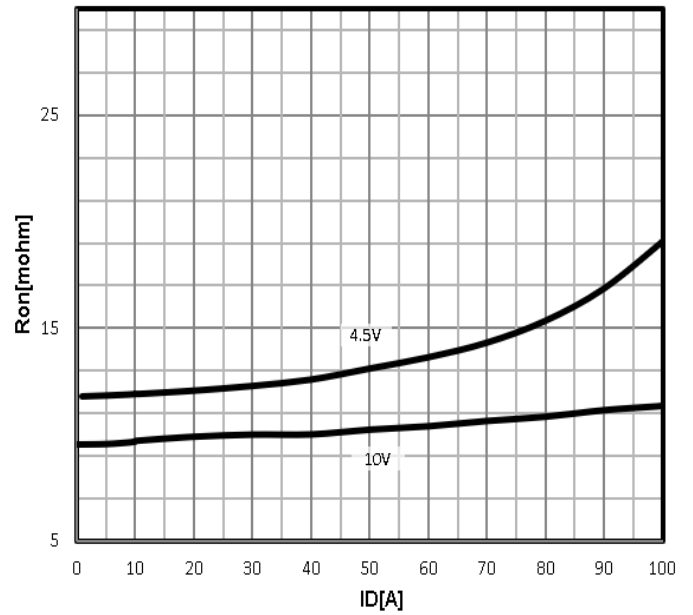
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Characteristics Curve:

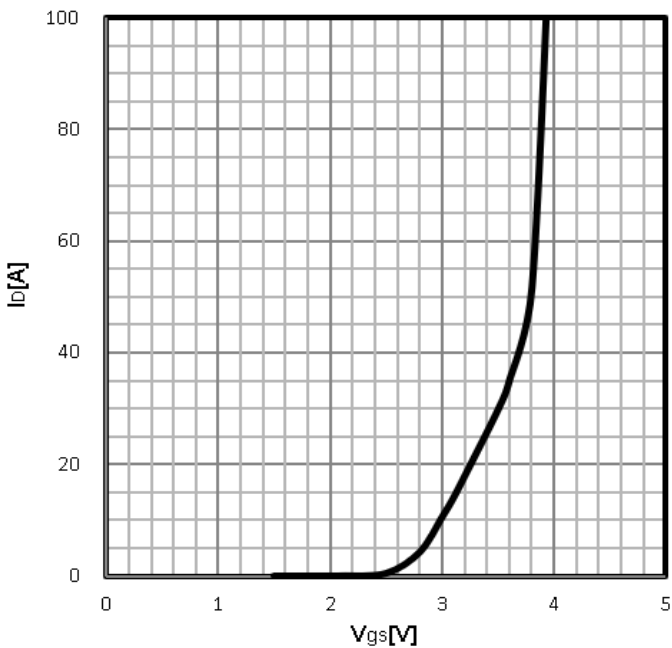
Typ. output characteristics
 $I_D=f(V_{DS})$



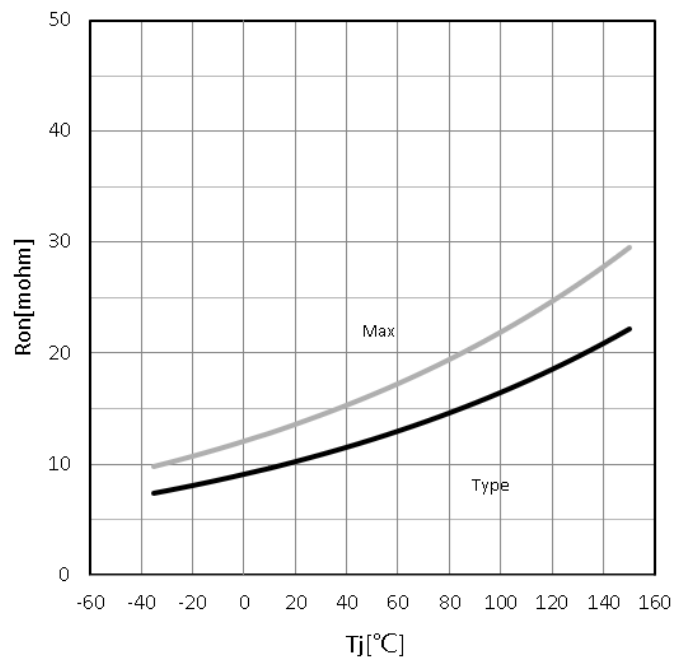
Typ. drain-source on resistance
 $R_{DS(on)}=f(I_D)$



Typ. transfer characteristics
 $I_D=f(V_{GS})$



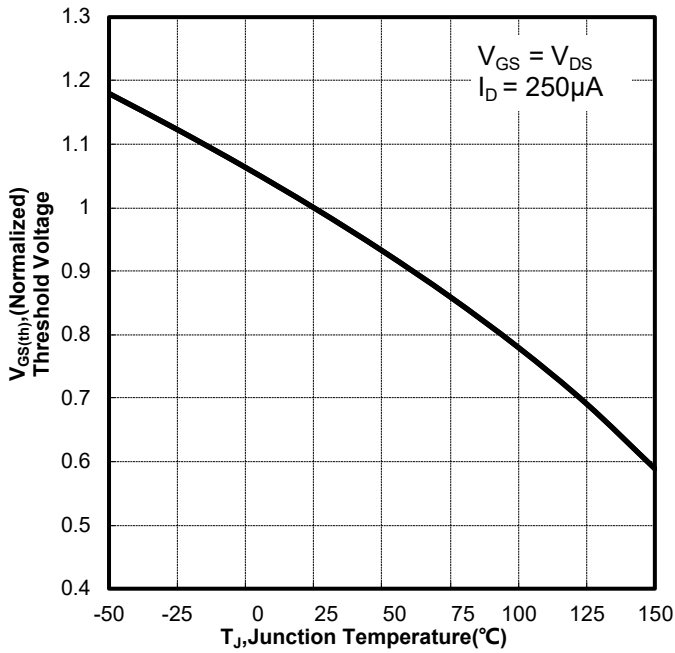
Drain-source on-state resistance
 $R_{DS(on)}=f(T_j); I_D=20A; V_{GS}=10V$



N-Ch 120V Fast Switching MOSFETs

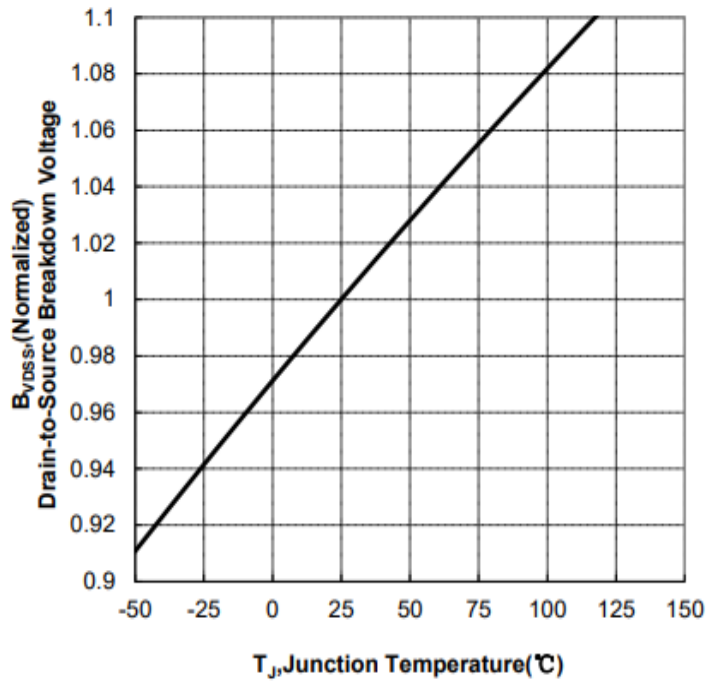
Gate Threshold Voltage

$V_{TH}=f(T_j); I_D=250\mu A$



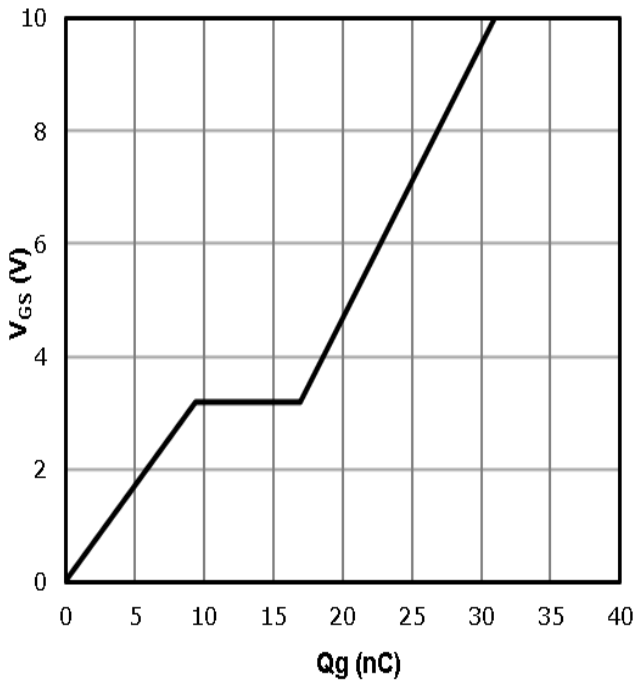
Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j); I_D=250\mu A$



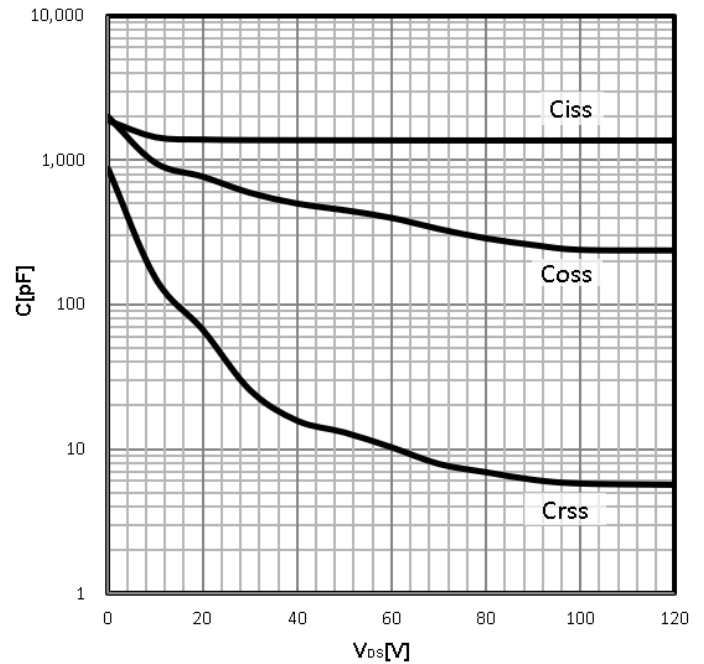
Typ. gate charge

$V_{GS}=f(Q_{gate})$

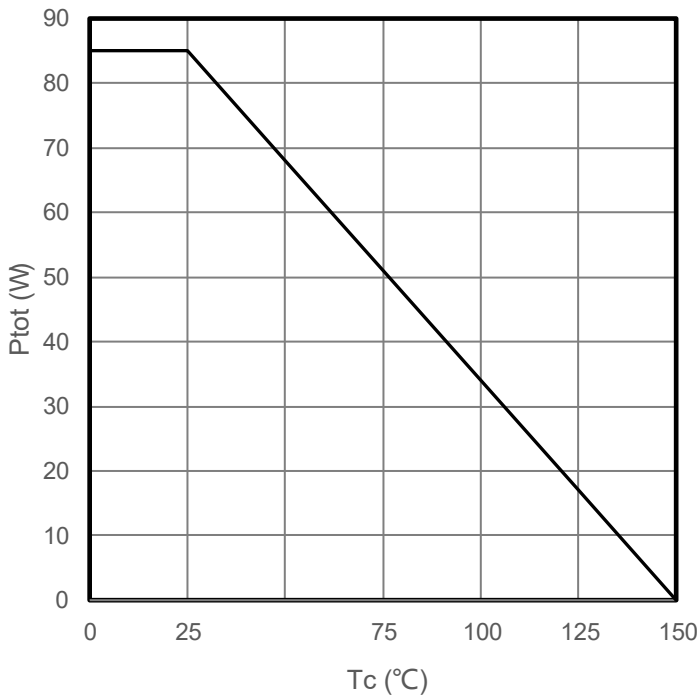


Typ. capacitances

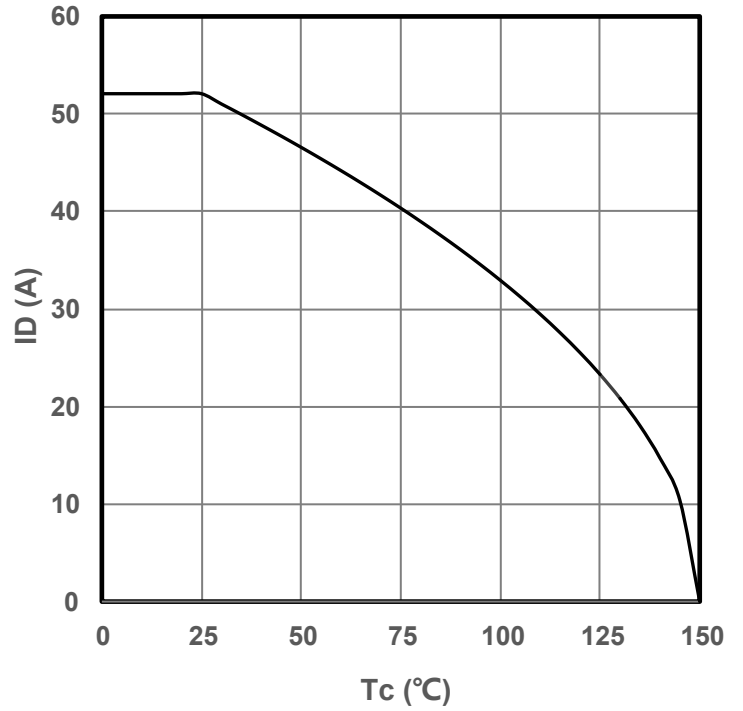
$C=f(V_{DS}); V_{GS}=0V; f$



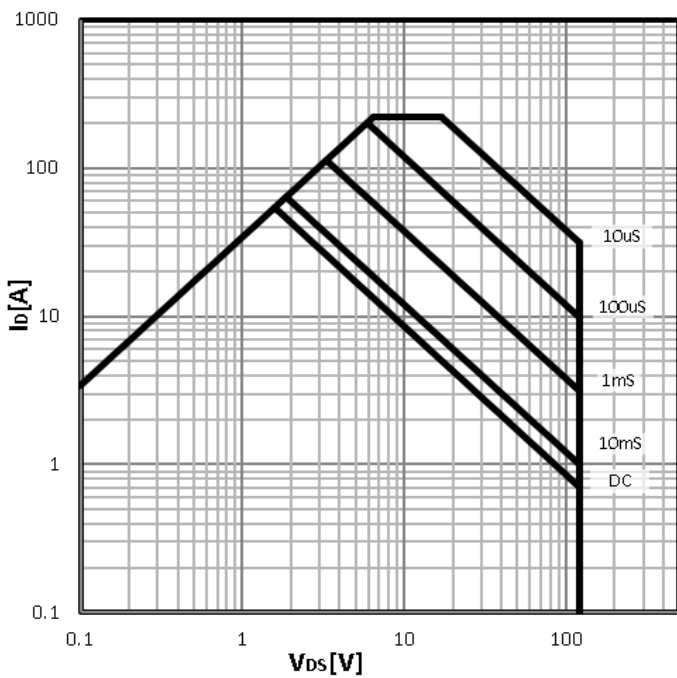
Power Dissipation
 $P_{tot}=f(T_j)$



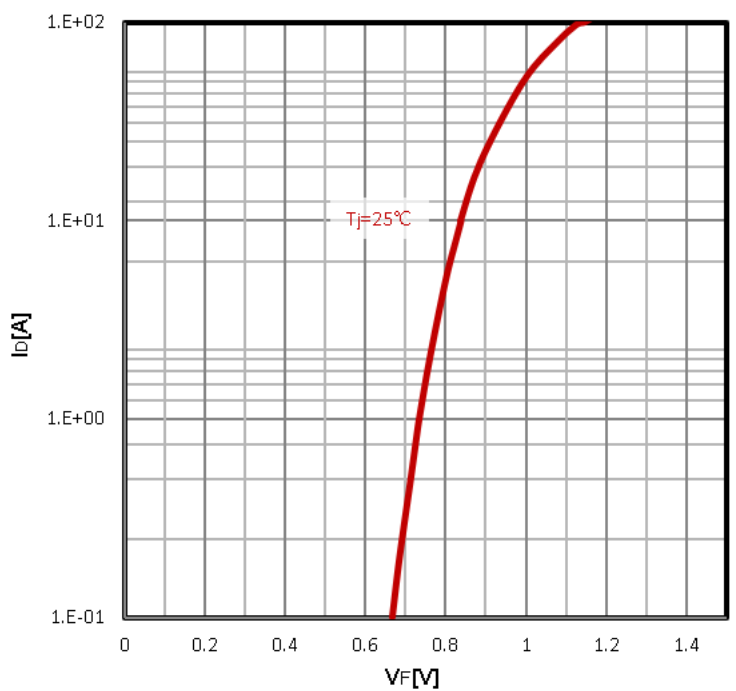
Maximum Drain Current
 $I_D=f(T_c)$



Safe operating area
 $I_D=f(V_{DS})$

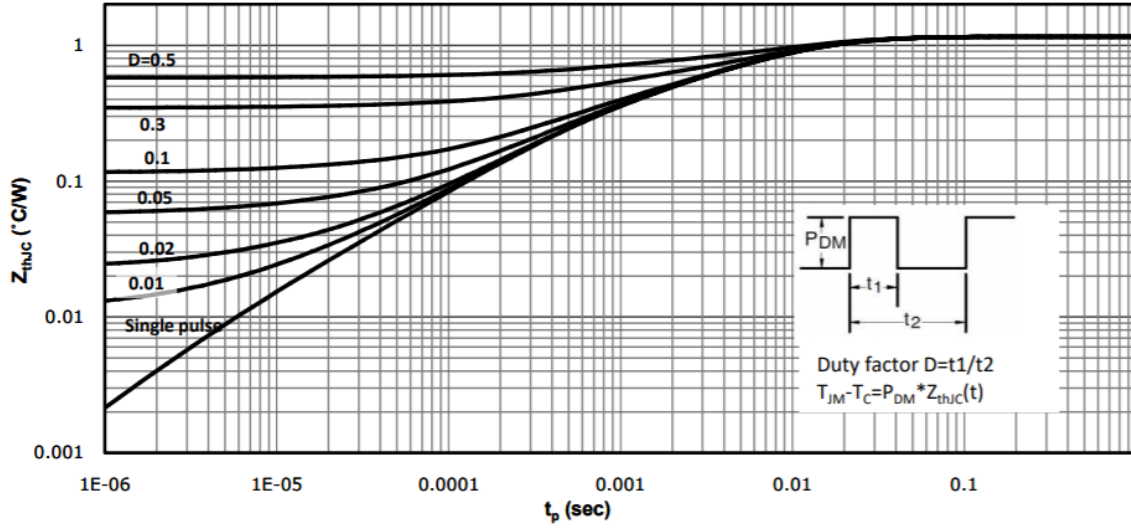


Body Diode Forward Voltage Variation
 $I_F=f(V_{GS})$

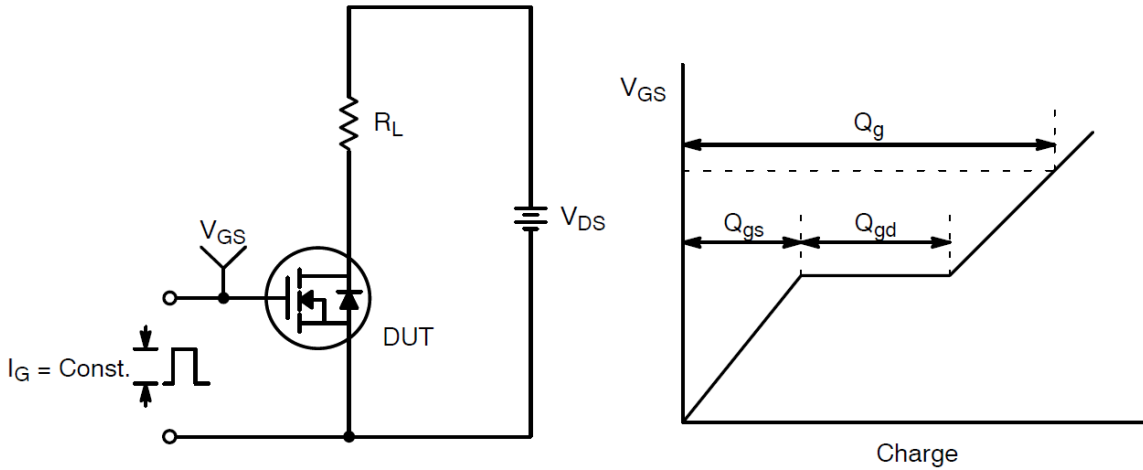


Max. transient thermal impedance

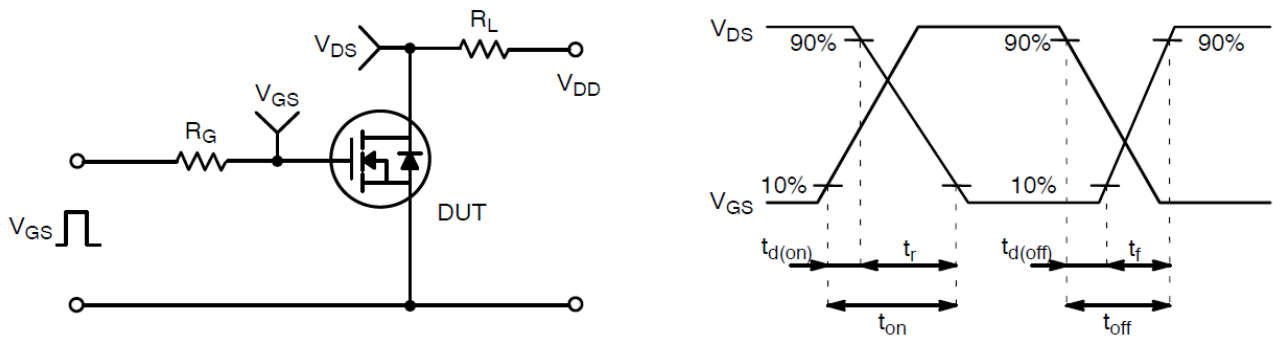
$$Z_{thJC} = f(t_p)$$



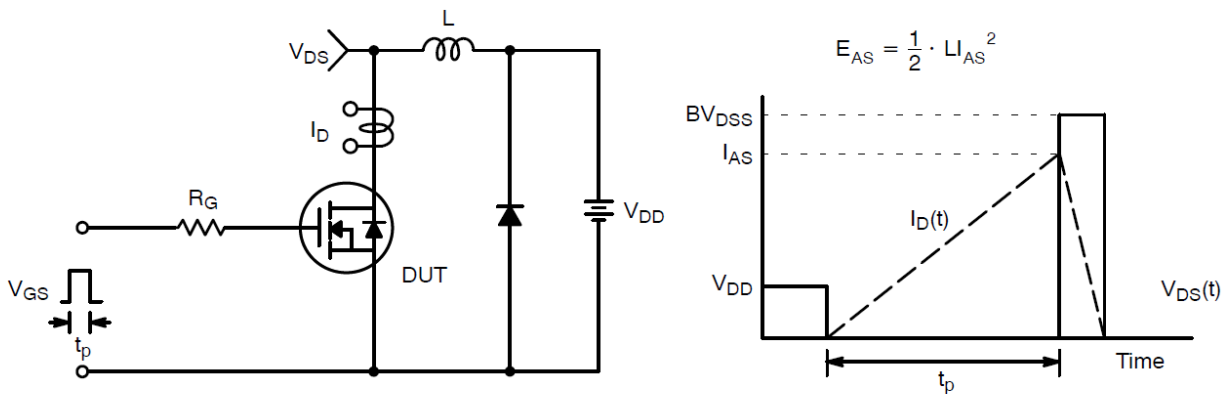
Test Circuit and Waveform:



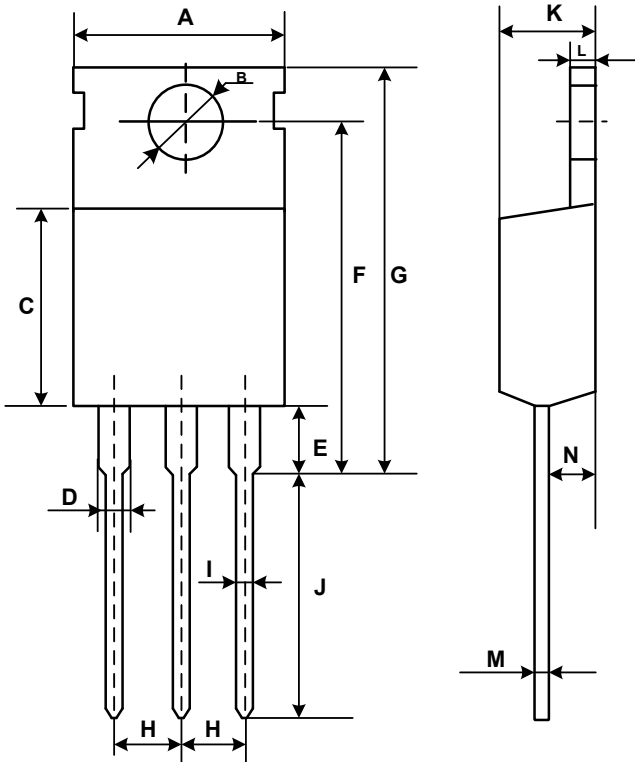
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

Mechanical Dimensions for TO-220
COMMON DIMENSIONS


SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.50
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60